

*Refile
1.124
20*

--22. A method of making a dielectric layer between a pair of opposing electrodes comprising the steps of:

forming, as said dielectric layer, an epitaxial thin film on a textured substrate;
forming one of said electrodes on an exposed surface of said thin film;
wholly or partially removing said textured substrate; and
forming an electrical connection to access said dielectric layer on the side of said textured substrate.

23.

The method according to Claim 22 wherein the textured substrate comprises nickel.

24.

The method according to Claim 22 wherein said epitaxial thin film is formed from perovskite.

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